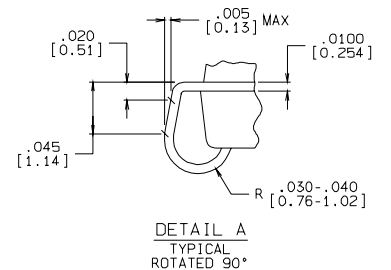
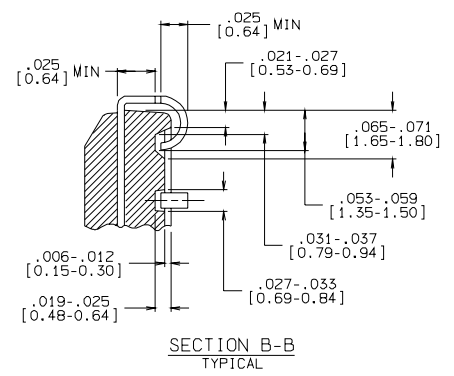
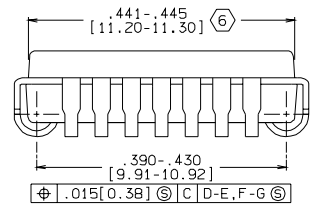
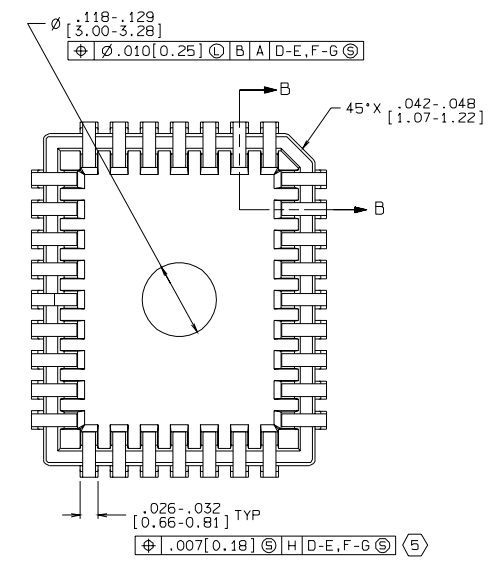
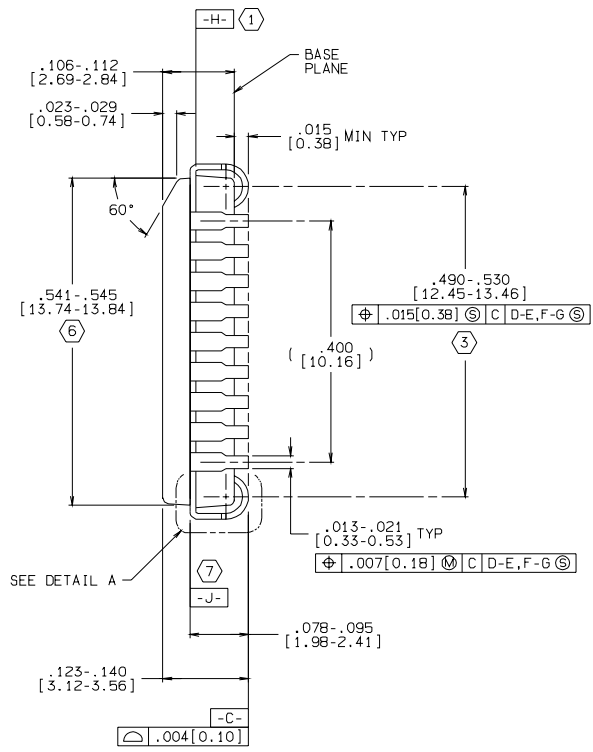
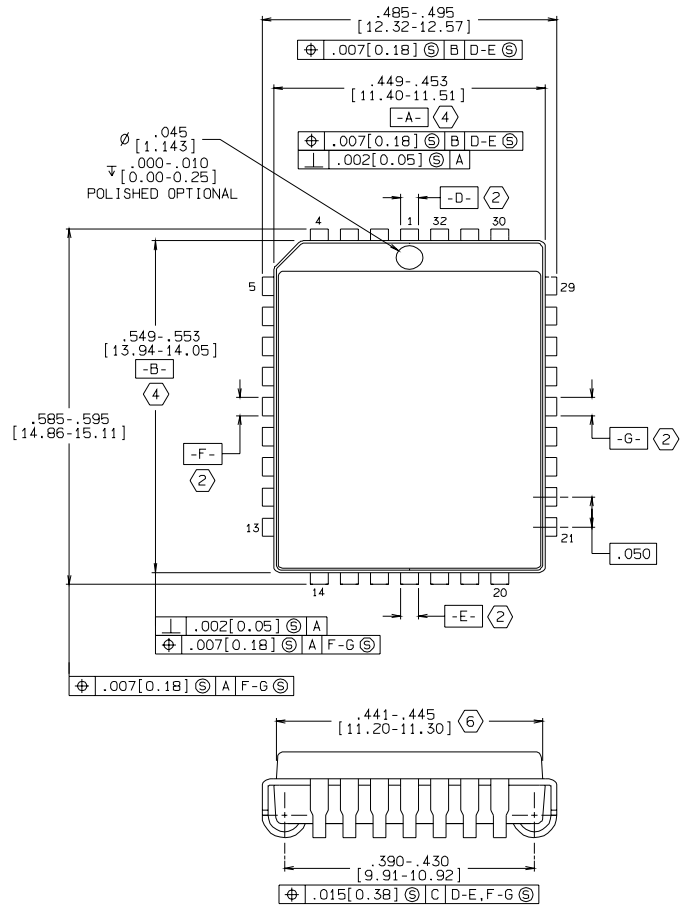


REVISIONS				
LTN	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09322	09/30/92	MS/SL
B	ADD FRONT VIEW NOTE B VARIATION AE WAS AZ	09868	06/30/93	MS/SL
C	ADD DIM .441-.445 [11.20-11.30]; REVISE NOTE 4 AND 6	10328	02/25/94	MS/



- NOTES: UNLESS OTHERWISE SPECIFIED
- DATUM PLANE -H- LOCATED AT BOTTOM OF MOLD PARTING LINE AND COINCIDENT WITH BOTTOM OF LEAD, WHERE LEAD EXITS PLASTIC BODY.
 - DATUM D-E AND F-G TO BE DETERMINED WHERE CENTER LEADS EXIT PLASTIC BODY AT DATUM PLANE -H-.
 - TO BE DETERMINED AT SEATING PLANE -C-.
 - DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DO INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .008 PER SIDE.
 - LOCATION TO DATUMS -A- AND -B- TO BE DETERMINED AT PLANE -H-.
 - DIMENSIONS ARE MEASURED AT DATUM PLANE -J-.
 - DATUM PLANE -J- LOCATED AT TOP OF MOLD PARTING LINE AND COINCIDENT WITH TOP OF LEAD, WHERE LEAD EXITS PLASTIC BODY.
 - REFERENCE JEDEC REGISTRATION MO-052, VARIATION AE, DATED 8/01/85.

APPROVALS		DATE	CONTROLLING DIMENSION: INCH	
DRAWN: MARTA SUCHY		09/30/92	NATIONAL SEMICONDUCTOR CORPORATION	
DFTG. CHK.			2800 Semiconductor Drive, Santa Clara, CA 95052-8090	
ENGR. CHK.			PLASTIC CHIP CARRIER,	
APPROVAL			32 LEAD,	
			RECTANGULAR	
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		N/A	D	MKT-V32A
		DO NOT SCALE DRAWING		SHEET 1 OF 1